

IN THE CLAIMS

Cancel claims 1-12 and 19-39 and 43.

1 - 12 (Canceled)

13. (Original) A method of bonding a first body to a second body comprising the steps of:

disposing between the first body and the second body, a freestanding reactive multilayer foil;

pressing the bodies together against the foil; and

igniting the reactive foil.

14. (Original) The method of claim 13 wherein at least one of the bodies is a semiconductor or microelectronic device.

15. (Original) The method of claim 13 wherein the reactive multilayer foil has a thickness in excess of 10 μ m.

16. (Original) The method of claim 13 wherein the bodies have coefficients of thermal expansion differing by at least 1 μ m/m/ $^{\circ}$ C.

17. (Original) The method of claim 13 wherein the first body comprises metal and the second body comprises ceramic material.

18. (Original) The product made by the method of claim 13.

19 - 39 (Canceled)

40. (Original) A method of bonding a first body to a second comprising the steps of:

disposing between the first body and the second body, a freestanding reactive multilayer foil and at least one layer of meltable joining material;

pressing the bodies together against the foil and joining material; and

igniting the reactive foil to melt the joining material.

41. (Original) The method of claim 40 wherein the joining material is coated on the foil.

42. (Original) The method of claim 40 wherein the joining material is freestanding.

43. (Canceled)